



TESSERA 3.0-078 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Applicant of  
Joseph Fjelstad

Group Art Unit: 2811

Application Serial No. 09/020,647 ✓

Examiner: Unassigned

Filed: February 9, 1998

Date: May 1, 1998

For: **METHOD OF MAKING A  
SEMICONDUCTOR CHIP PACKAGE**

X

Assistant Commissioner For Patents  
Washington, D.C. 20231

SUPPLEMENTAL PRELIMINARY AMENDMENT

Sir:

Further to the Preliminary Amendment filed February 9, 1998, please  
amend the above-identified application as follows:

In the Claims:

Add new claims 21-34 as follows:

21. A method of making a compliant microelectronic assembly  
comprising the steps of:  
providing a microelectronic element having a first surface and a plurality  
of contacts disposed on the first surface thereof;  
providing a compliant layer over the first surface of said microelectronic  
element, said compliant layer having a bottom surface facing toward said first surface  
of said microelectronic element, a top surface facing upwardly away from said

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*Michael J. Doherty*  
(Signature)

MICHAEL J. DOHERTY

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